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- AC Types Feature 1.5-V to 5.5-V Operation and Balanced Noise Immunity at 30% of the Supply Voltage
- Buffered Inputs
- Incorporate Two Enable Inputs to Simplify Cascading and/or Data Reception
- Speed of Bipolar F, AS, and S, With Significantly Reduced Power Consumption
- Balanced Propagation Delays
- ±24-mA Output Drive Current
  Fanout to 15 F Devices
- SCR-Latchup-Resistant CMOS Process and Circuit Design
- Exceeds 2-kV ESD Protection Per MIL-STD-883, Method 3015

#### description/ordering information

The 'ACT139 devices are dual 2-line to 4-line decoders/demultiplexers designed for 4.5-V to 5.5-V  $V_{CC}$  operation. These devices are designed to be used in high-performance memory-decoding or data-routing applications requiring very short propagation delay times. In high-performance memory systems, these decoders can be used to minimize the effects of system decoding. When used with high-speed memories utilizing a fast enable circuit, the delay times of these decoders and the enable time of the memory usually are less than the typical access time of the memory. This means that the effective system delay introduced by the decoders is negligible.

The active-low enable ( $\overline{G}$ ) input can be used as a data line in demultiplexing applications. These decoders/demultiplexers feature fully buffered inputs, each of which represents only one normalized load to its driving circuit.

TA	PACK	AGE <sup>†</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING		
PDIP – E	PDIP – E	Tube	CD74ACT139E	CD74ACT139E		
–55°C to 125°C	SOIC – M	Tube	CD74ACT139M	ACT139M		
-55 C 10 125 C	30IC – M	Tape and reel	CD74ACT139M96	ACTIS9W		
	CDIP – F	Tube	CD54ACT139F3A	CD54ACT139F3A		

#### **ORDERING INFORMATION**

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



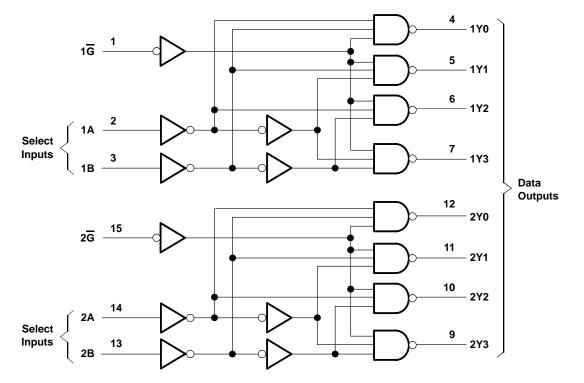
Copyright © 2003, Texas Instruments Incorporated On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

CD54AC1	[139	.F P	ACKAGE								
CD74ACT13	9E	OR I	M PACKAGE								
(TOP VIEW)											
			1.17								
1 <mark>G</mark> [	1	16	V <u>c</u> c   2G								
1A [	2	15	2 <u>G</u>								
1B [	3	14	2A								
1Y0 [	4	13	2B								
1Y1 [	5	12	2Y0								
1Y2 [	6	11	2Y1								
1Y3 [	7	10	2Y2								
GND [	8	9	2Y3								

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	FUNCTION TABLE (each decoder/demultiplexer)										
G	SEL	ЕСТ		-015							
G	В	Α	Y0	Y1	Y2	Y3					
н	Х	Х	Н	Н	Н	Н					
L	L	L	L	Н	Н	н					
L	L	Н	Н	L	Н	н					
L	н	L	н	Н	L	н					
L	Н	Н	Н	Н	Н	L					

### logic diagram (positive logic)



#### absolute maximum ratings over operating free-air temperature range<sup>†</sup>

Supply voltage range, V <sub>CC</sub>	–0.5 V to 6 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (see Note 1)	
Output clamp current, $I_{OK}$ (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> ) (see Note 1)	±50 mA
Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$	±50 mA
Continuous current through V <sub>CC</sub> or GND	±100 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): E package	67°C/W
M package	73°C/W
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



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#### recommended operating conditions (see Note 3)

		T <sub>A</sub> =	25°C	–55° 125		–40° 85°		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
VCC	Supply voltage	4.5	5.5	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2		2		2		V
VIL	Low-level input voltage		0.8		0.8		0.8	V
VI	Input voltage	0	VCC	0	VCC	0	VCC	V
VO	Output voltage	0	VCC	0	VCC	0	VCC	V
ЮН	High-level output current		-24		-24		-24	mA
IOL	Low-level output current		24		24		24	mA
$\Delta t / \Delta v$	Input transition rise or fall rate		10		10		10	ns/V

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CON	DITIONS	Vcc	T <sub>A</sub> = 25°C			–55°C to 125°C		C to C	UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	
		lOH = -50 μA	4.5 V	4.4		4.4		4.4		
Vau	$\lambda = \lambda = 0$	I <sub>OH</sub> = -24 mA	4.5 V	3.94		3.7		3.8		V
VOH	$V_I = V_{IH} \text{ or } V_{IL}$	I <sub>OH</sub> = -50 mA†	5.5 V			3.85				v
		I <sub>OH</sub> = -75 mA <sup>†</sup>	5.5 V					3.85		
		I <sub>OL</sub> = 50 μA	4.5 V		0.1		0.1		0.1	
Vei	$\lambda = \lambda = 0$	I <sub>OL</sub> = 24 mA	4.5 V		0.36		0.5		0.44	V
VOL	$V_I = V_{IH} \text{ or } V_{IL}$	I <sub>OL</sub> = 50 mA <sup>†</sup>	5.5 V				1.65			v
		I <sub>OL</sub> = 75 mA <sup>†</sup>	5.5 V						1.65	
Ц	$V_I = V_{CC} \text{ or } GND$		5.5 V		±0.1		±1		±1	μA
ICC	$V_I = V_{CC} \text{ or } GND,$	I <mark>O</mark> = 0	5.5 V		8		160		80	μA
$\Delta I_{CC}^{\ddagger}$	$V_{I} = V_{CC} - 2.1 V$		4.5 V to 5.5 V		2.4		3		2.8	mA
Ci					10		10		10	pF

<sup>†</sup> Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 50-Ω transmission-line drive capability at 85°C and 75-Ω transmission-line drive capability at 125°C.
 <sup>‡</sup> Additional quiescent supply current per input pin, TTL inputs high, 1 unit load

#### ACT INPUT LOAD TABLE

INPUT	UNIT LOAD
A or B	1
G	0.67

Unit Load is  $\Delta I_{CC}$  limit specified in electrical characteristics table (e.g., 2.4 mA at 25°C).



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# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

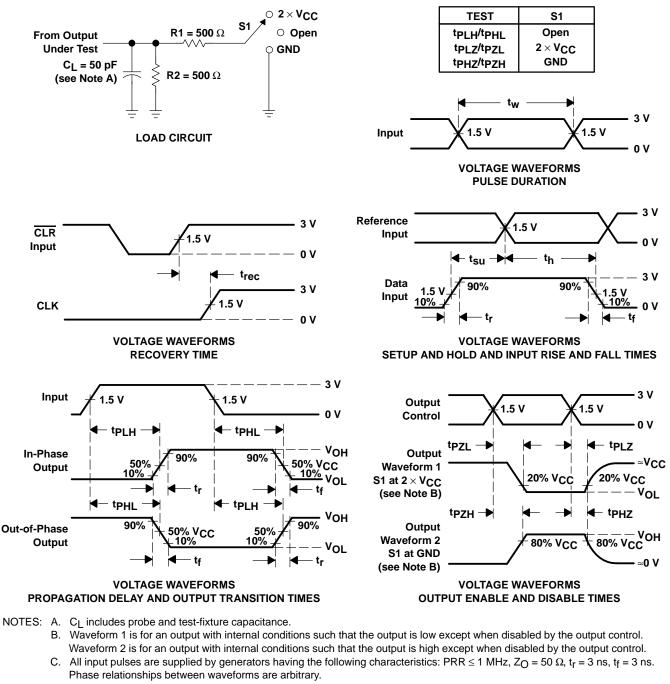
PARAMETER	FROM (INPUT)	ТО (О <b>U</b> ТРUТ)	–55°C to 125°C		–40° 85°	UNIT	
	(INPUT)	(001F01)	MIN	MAX	MIN	MAX	
<sup>t</sup> PLH	A or B	Y	2.9	11.5	3.1	10.5	ns
<sup>t</sup> PHL	A B		2.9	11.5	3.1	10.5	115
<sup>t</sup> PLH	G	~	3	12	3.2	10.9	ns
<sup>t</sup> PHL	0	-	3	12	3.2	10.9	115

### operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance	83	pF

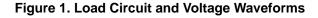


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PARAMETER MEASUREMENT INFORMATION

- D. For clock inputs, f<sub>max</sub> is measured with the input duty cycle at 50%.
- E. The outputs are measured one at a time with one input transition per measurement.
- F. tPLH and tPHL are the same as tpd.
- G.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- H. tpLz and tpHz are the same as tdis.
- I. All parameters and waveforms are not applicable to all devices.







#### PACKAGING INFORMATION

Orderable Device	Status	Package Type	•	Pins	•	Eco Plan	Lead finish/	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	Ball material	(3)		(4/5)	
							(6)				
CD54ACT139F3A	ACTIVE	CDIP	J	16	1	Non-RoHS	SNPB	N / A for Pkg Type	-55 to 125	CD54ACT139F3A	Samples
						& Green					· ·
CD74ACT139E	ACTIVE	PDIP	Ν	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74ACT139E	Samples
											Bumpies
CD74ACT139M	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	ACT139M	Samples
CD74ACT139M96	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	ACT139M	
CD74ACT TS9M96	ACTIVE	3010	D	10	2500	KUHS & Gleen	NIFDAU	Level-1-200C-UNLIW	-55 10 125	ACTISSM	Samples
CD74ACT139ME4	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	ACT139M	Samples
											Samples
CD74ACT139MG4	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	ACT139M	Samples
											T. T

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.



# PACKAGE OPTION ADDENDUM

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#### OTHER QUALIFIED VERSIONS OF CD54ACT139, CD74ACT139 :

- Catalog : CD74ACT139
- Military : CD54ACT139

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

# PACKAGE MATERIALS INFORMATION

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#### TAPE AND REEL INFORMATION





## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal	
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Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74ACT139M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1



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# PACKAGE MATERIALS INFORMATION

5-Jan-2022



\*All dimensions are nominal

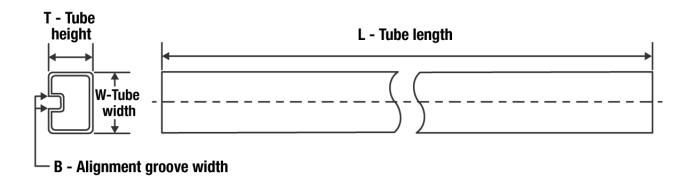
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74ACT139M96	SOIC	D	16	2500	340.5	336.1	32.0



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### TUBE



*All	dimensions	are	nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
CD74ACT139E	N	PDIP	16	25	506	13.97	11230	4.32
CD74ACT139E	N	PDIP	16	25	506	13.97	11230	4.32
CD74ACT139M	D	SOIC	16	40	507	8	3940	4.32
CD74ACT139ME4	D	SOIC	16	40	507	8	3940	4.32
CD74ACT139MG4	D	SOIC	16	40	507	8	3940	4.32

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



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# D (R-PDSO-G16) PLASTIC SMALL OUTLINE Stencil Openings (Note D) Example Board Layout (Note C) –16x0,55 -14x1,27 -14x1,27 16x1,50 5,40 5.40 Example Non Soldermask Defined Pad Example Pad Geometry (See Note C) 0,60 .55 Example 1. Solder Mask Opening (See Note E) -0,07 All Around

NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



J (R-GDIP-T\*\*) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

# N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- $\triangle$  The 20 pin end lead shoulder width is a vendor option, either half or full width.



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